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AMENDMENTS TO THE CLAIMS:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-26 are cancelled.

27. (New) A wafer double-side polishing apparatus comprising at least a carrier plate having wafer holding holes; upper and lower turn tables to which polishing pads are attached; and a slurry supply means; with wafers held in the wafer holding holes, the carrier plate being moved between the upper and lower turn tables while supplying slurry, to simultaneously polish both front and back surfaces of wafers, wherein a PCD of upper turn table load supporting points that is a diameter of a circle joining load supporting points of the upper turn table coincides with a PCD of centers of the wafer holding holes on the carrier plate that is a diameter of a circle joining each center of the wafer holding holes on the carrier plate.

28. (New) The wafer double-side polishing apparatus according to claim 27, wherein the motion of the carrier plate is a circular motion not accompanied by rotation of the carrier plate.

29. (New) A wafer double-side polishing apparatus comprising at least a plurality of carrier plates each having wafer holding holes; sun and internal gears for rotating and revolving the carrier plates; upper and lower turn tables to which polishing pads are attached; and a slurry supply means; with wafers held in the wafer holding holes, the plurality of carrier plates being rotated and revolved between the upper and lower turn tables while supplying slurry, to simultaneously polish both front and back surfaces of wafers, wherein a PCD of upper turn table load supporting points that is a diameter of a circle joining load supporting points of the upper turn table coincides with a PCD of carrier plate centers that is a diameter of a circle joining the centers of the plurality of carrier plates.

30. (New) The wafer double-side polishing apparatus according to claim 27, wherein a PCD of lower turn table load supporting points that is a diameter of a circle joining load supporting points of the lower turn table coincides with the PCD of the upper turn table load supporting points.
31. (New) The wafer double-side polishing apparatus according to claim 29, wherein a PCD of lower turn table load supporting points that is a diameter of a circle joining load supporting points of the lower turn table coincides with the PCD of the upper turn table load supporting points.
32. (New) A wafer double-side polishing method comprising holding wafers on a carrier plate on which are formed wafer holding holes for holding wafers; and, while supplying slurry, moving the carrier plate between upper and lower turn tables to which polishing pads are attached, to simultaneously polish both front and back surfaces of the wafers, wherein the wafers are polished with causing a PCD of upper turn table load supporting points that is a diameter of a circle joining load supporting points of the upper turn table and a PCD of wafer centers that is a diameter of a circle joining centers of the wafers held by the carrier plate to coincide with each other.
33. (New) The wafer double-side polishing method according to claim 32, wherein the motion of the carrier plate is a circular motion not accompanied by rotation of the carrier plate.
34. (New) A wafer double-side polishing method comprising holding wafers on a plurality of carrier plates each having thereon formed holding holes for holding wafers; and, while supplying slurry, rotating and revolving the plurality of carrier plates using sun and internal gears between upper and lower turn tables to which polishing pads are attached, to simultaneously polish both front and back surfaces of the wafers, wherein the wafers are polished with causing a PCD of upper turn table load supporting points that is a diameter of a circle joining load supporting points of the upper turn

table and a PCD of carrier plate centers that is a diameter of a circle joining centers of the plurality of carrier plates to coincide with each other.

35. (New) The wafer double-side polishing method according claim 32, wherein a PCD of lower turn table load supporting points that is a diameter of a circle joining load supporting points of the lower turn table is caused to coincide with the PCD of the upper turn table load supporting points.

36. (New) The wafer double-side polishing method according claim 34, wherein a PCD of lower turn table load supporting points that is a diameter of a circle joining load supporting points of the lower turn table is caused to coincide with the PCD of the upper turn table load supporting points.

37. (New) The wafer double-side polishing method according to claim 32, wherein during the wafer polishing, the wafers are polished while controlling polishing conditions.

38. (New) The wafer double-side polishing method according to claim 34, wherein during the wafer polishing, the wafers are polished while controlling polishing conditions.

39. (New) The wafer double-side polishing method according to claim 37, wherein the polishing condition control is performed by controlling the temperature of the upper turn table and/or the lower turn table.

40. (New) The wafer double-side polishing method according to claim 38, wherein the polishing condition control is performed by controlling the temperature of the upper turn table and/or the lower turn table.

41. (New) A wafer double-side polishing apparatus comprising at least a carrier plate having wafer holding holes; upper and lower turn tables to which polishing pads are attached; and a slurry supply means; with wafers held in the wafer holding holes, the carrier plate being moved between the upper and lower turn tables while supplying slurry, to simultaneously polish both front and back surfaces of wafers, wherein shape adjustment means are disposed at load supporting point portions of the upper turn table.

42. (New) The wafer double-side polishing apparatus according to claim 41, wherein the motion of the carrier plate is a circular motion not accompanied by rotation of the carrier plate.

43. (New) The wafer double-side polishing apparatus according to claim 41, wherein a PCD of upper turn table load supporting points that is a diameter of a circle joining load supporting points of the upper turn table coincides with a PCD of centers of the wafer holding holes on the carrier plate that is a diameter of a circle joining each center of the wafer holding holes on the carrier plate.

44. (New) A wafer double-side polishing apparatus, comprising at least a plurality of carrier plates each having wafer holding holes; sun and internal gears for rotating and revolving the carrier plates; upper and lower turn tables to which polishing pads are attached; and a slurry supply means; with wafers held in the wafer holding holes, the plurality of carrier plates being rotated and revolved between the upper and lower turn tables while supplying slurry, to simultaneously polish both front and back surfaces of wafers, wherein shape adjustment means are disposed at load supporting point portions of the upper turn table.

45. (New) The wafer double-side polishing apparatus according to claim 44, wherein a PCD of upper turn table load supporting points that is a diameter of a circle joining load supporting points of

the upper turn table coincides with a PCD of carrier plate centers that is a diameter of a circle joining centers of the plurality of carrier plates.

46. (New) The wafer double-side polishing apparatus according to claim 41, wherein the shape adjustment means are micrometers.

47. (New) The wafer double-side polishing apparatus according to claim 44, wherein the shape adjustment means are micrometers.

48. (New) The wafer double-side polishing apparatus according to claim 41, wherein materials of the turn tables are stainless steel.

49. (New) The wafer double-side polishing apparatus according to claim 44, wherein materials of the turn tables are stainless steel.

50. (New) A wafer double-side polishing method comprising holding wafers in wafer holding holes formed on a carrier plate; and while supplying slurry, moving the carrier plate between upper and lower turn tables to which polishing pads are attached, to simultaneously polish both front and back surfaces of the wafers, wherein the wafers are polished while controlling the turn table shape by adjusting the slurry supply amount.

51. (New) The wafer double-side polishing method according to claim 50, wherein the motion of the carrier plate is a circular motion not accompanied by rotation of the carrier plate.

52. (New) A wafer double-side polishing method comprising holding wafers on a plurality of carrier plates each having thereon formed holding holes for holding wafers; and while supplying slurry, rotating and revolving the plurality of carrier plates using sun and internal gears between upper and lower turn tables to which polishing pads are attached, to simultaneously polish both front and back surfaces of the wafers, wherein the wafers are polished while controlling the turn table shape by adjusting the slurry supply amount.

53. (New) The wafer double-side polishing method according to claim 50, wherein the slurry supply amount is adjusted depending on usage time of the polishing pads.

54. (New) The wafer double-side polishing apparatus according to claim 52, wherein materials of the turn tables are stainless steel.

55. (New) A wafer double-side polishing method comprising holding wafers in wafer holding holes formed on a carrier plate; and while supplying slurry, moving the carrier plate between upper and lower turn tables to which polishing pads are attached, to simultaneously polish both front and back surfaces of the wafers, wherein shape adjustment means are disposed at load supporting point portions of the upper turn table, and wherein the wafers are polished while controlling the turn table shape by adjusting the shape adjustment means.

56. (New) The wafer double-side polishing method according to claim 55, wherein the motion of the carrier plate is a circular motion not accompanied by rotation of the carrier plate.

57. (New) A wafer double-side polishing method comprising holding wafers on a plurality of carrier plates each having thereon formed holding holes for holding wafers; and while supplying

slurry, rotating and revolving the plurality of carrier plates using sun and internal gears between upper and lower turn tables to which polishing pads are attached, to simultaneously polish both front and back surfaces of the wafers, wherein shape adjustment means are disposed at load supporting point portions of the upper turn table, and wherein the wafers are polished while controlling the turn table shape by adjusting the shape adjustment means.

58. (New) The wafer double-side polishing method according to claim 55, wherein the wafers are polished while controlling the turn table shape by adjusting supply amount of the slurry supplied.

59. (New) The wafer double-side polishing method according to claim 57, wherein the wafers are polished while controlling the turn table shape by adjusting supply amount of the slurry supplied.

60. (New) The wafer double-side polishing method according to claim 50, wherein the wafers are polished with causing a PCD of upper turn table load supporting points that is a diameter of a circle joining load supporting points of the upper turn table and a PCD of wafer centers that is a diameter of a circle joining centers of the wafers held by the carrier plate to coincide with each other, or causing the PCD of upper turn table load supporting points and a PCD of carrier plate centers that is a diameter of a circle joining centers of the plurality of carrier plates to coincide with each other.

61. (New) The wafer double-side polishing method according to claim 52, wherein the wafers are polished with causing a PCD of upper turn table load supporting points that is a diameter of a circle joining load supporting points of the upper turn table and a PCD of wafer centers that is a diameter of a circle joining centers of the wafers held by the carrier plate to coincide with each other, or causing the PCD of upper turn table load supporting points and a PCD of carrier plate centers that is a diameter of a circle joining centers of the plurality of carrier plates to coincide with each other.

62. (New) The wafer double-side polishing method according to claim 55, wherein the wafers are polished with causing a PCD of upper turn table load supporting points that is a diameter of a circle joining load supporting points of the upper turn table and a PCD of wafer centers that is a diameter of a circle joining centers of the wafers held by the carrier plate to coincide with each other, or causing the PCD of upper turn table load supporting points and a PCD of carrier plate centers that is a diameter of a circle joining centers of the plurality of carrier plates to coincide with each other.

63. (New) The wafer double-side polishing method according to claim 57, wherein the wafers are polished with causing a PCD of upper turn table load supporting points that is a diameter of a circle joining load supporting points of the upper turn table and a PCD of wafer centers that is a diameter of a circle joining centers of the wafers held by the carrier plate to coincide with each other, or causing the PCD of upper turn table load supporting points and a PCD of carrier plate centers that is a diameter of a circle joining centers of the plurality of carrier plates to coincide with each other.